

**TFT LCD MODULE** 

1.28 inch 240RGB\*240DOTS

MODULE NUMBER:==GHD128001H12-V1

REVISION:==A

Customer:	
Approved by	
Approved by	

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### **REVISION HISTORY**

1.0 Initial Release All	2023-2-17
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### 1. GENERAL DESCRIPTION

#### 1.1 DESCRIPTION

GHD128001H12-V1 is a transmissive type color active matrix TFT (Thin Film Transistor) liquid crystal display (LCD) that uses amorphous silicon TFT as a switching device. This model is composed of a TFT-LCD module (TFT-LCD panel, driver IC and FPC), a back-light unit and. The resolution of 1.28" contains 240 RGB X240 pixels and can display up to 262k colors.

### 1.2 GENERAL INFORMATION

Items	Specification	Unit	Note
Drive element	a-Si TFT	-	(×0 -
LCM outline size	37.74 (H) x 35.59 (V)x 1.6(D)	mm	
Active area	32.4 (H) x 32.4 (V)	mm	-
Number of pixels	240(H)X240(V)	pixels	-
Pixel arrangement	RGB Vertical stripe	-	-
Pixel Pitch	0.135x 0.135	um	-
Display color	262k	color	-
Viewing direction	ALL	-	-
Controller / Driver	GC9A01	-	-
Data interface	SPI 4W	-	
Backlight	2 White LEDs In Parallels	-	
Weight	TBD	g	

### 2. ABSOLUTE MAXIMUM RATING

(Ta=25±2°C, Vss=GND=0V)

Characteristics	Symbol	Min.	Тур	Max.	Uni t	Notes
Cupply Voltage	IOVCC	-0.3	-	4.6	V	
Supply Voltage	VCI	-0.3	1	4.6	٧	
TFT Gate On voltage	VGH	-0.3	1	27	٧	
TFT Gate Off voltage	VGL	-0.3	-	27	٧	
Backlight Forward Current	l <sub>F</sub>	-		20	mA	
Operating Temperature	T <sub>OPR</sub>	-20		+70	°C	(1), (3)
Storage Temperature	T <sub>STG</sub>	-30		+80	°C	(2), (3)
Humidity	RH	-	. (	90	%	Max. 60 °C

#### Notes:

- (1) In case of below 0°C, the response time of liquid crystal (LC) becomes slower and the color of panel becomes darker than normal one. Level of retardation depends on temperature, because of the LC characteristics.
- (2) If product is exposed to high temperatures for extended time, there is a possibility of the polarizer film damage which could degrade the optical characteristics.
- (3) Permanent damage to the device may occur if maximum values are exceeded or reverse voltage is loaded.
  - Functional operation should be restricted to the conditions described under normal operating conditions.

### 3. ELECTRICAL CHARACTERISTICS

### 3.1 LCM DC CHARACTERISTICS

 $(Ta=25\pm2^{\circ}C)$ 

Characteristics	Sym bol	Min.	Тур.	Max.	Unit	Note
Power Supply Voltage 1	IOVC C	1.65	1.8	3.3	V	
Power Supply Voltage 2	VCI	2.5	2.8	3.3	V	
Gate Driver High Voltage	VGH	12	1	13	V	
Gate Driver Low Voltage	VGL	-11	-	-18	٧	
	I <sub>DD</sub>	-	TBD		mA	Normal mode
Current Consumption	I <sub>DD-SL</sub> EEP		TBD		uA	Sleep mode
Input voltage "L" Level	V <sub>IL</sub>	GND	<del>-</del> (	0.3IOVCC	V	IOVCC=1.65~
Input voltage "H" Level	V <sub>IH</sub>	0.7IOVCC	3	IOVCC	V	3.3
Output voltage "L" Level	$V_{oL}$	GND	-	0.2IOVCC	V	I <sub>OL</sub> =1mA
Output voltage "H" Level	V <sub>oH</sub>	0.8IOVCC	-	IOVCC	V	I <sub>OH</sub> =-1mA

### 3.2 BACK-LIGHT UNIT CHARACTERISTICS

The back-light system is an edge-lighting type with 4 white LEDs. The characteristics of the back-light are shown in the following tables.

 $(Ta=25\pm2^{\circ}C)$ 

Characteristics	Symbol	Condition	Min.	Type	Max.	Unit	Notes
Forward Voltage	Vf	I∟=20mA	ı	6.0	ı	V	1
Forward current	ΙL		ı	20	-	mA	1
Luminance	Lv	I∟=20mA	ı	500	1	cd/m <sup>2</sup>	1
LED life time	-	I∟=20mA	20,000	25,000	1	Hr	Note 1

#### Note:

(1) The "LED life time" is defined as the module brightness decrease to 50% of original brightness at  $I_L$ =20mA. The LED life time could be decreased if operating  $I_L$  is larger than 20mA.

Bcklight circuit diagram shown in below:



VF=6. OV IF=20mA

### 4. OPTICAL CHARACTERISTICS

The following items are measured under stable conditions. The optical characteristics should be measured in a dark room.

Measuring equipment: BM-5AS, BM-7, EZ-Contrast.

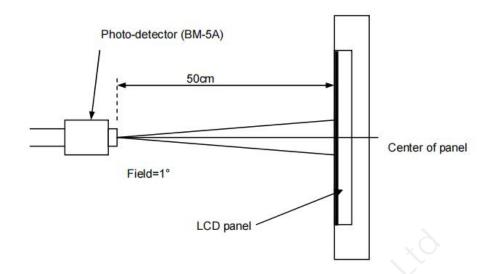
(Ta=25±2°C)

Parame	ter	Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Contrast Ratio (Center point)		C/R	-	700	720	-	-	BM-7 Note(2)
Luminance o (Center po		L <sub>w</sub>	B/L on	15%	TBD	15%	cd/m <sup>2</sup>	CA-210
Luminance ur	niformity	Uw		80	ı	_	%	BM-7 Note(3)
Response	Time	Tr + Tf		ı	30	35	ms	BM-5AS Note(4)
	White	W <sub>X</sub>	$\theta = 0$ .	1	0.308	-		
	vvriite	Wx	Normal viewing	-	0.331	-	_	CA-210 Note(5)
	Red	R <sub>X</sub>	angle B/L On Note(1)		0.641	-		
Color		R <sub>Y</sub>			0.337	-		
Chromaticity (CIE 1931)	Green	G <sub>X</sub>		<i>O</i> -	0.274	-		
		Gy		-	0.560	-		
	Dluc	B <sub>X</sub>	$(C_{O})$	-	0.141	-		
	Blue	By	O-*	-	0.113	-		
	Hon	θτ		-	80	-		
Viewing	Hor.	$\theta_{B}$	O/D> 40	-	80	-	D	EZ Contrast
Angle	Van	θι	C/R≥10	-	80	-	Deg	Note(6)
	Ver.	$\theta_{R}$		-	80	-		
Optima \	/iew Dire	ction			ALL			Note(7)

<sup>\*</sup> This condition will be changed by the evaluation circumstance. If product is exposed to high temperatures for extended time, there is a possibility of the polarizer film damage which could degrade the optical characteristics.

#### Notes:

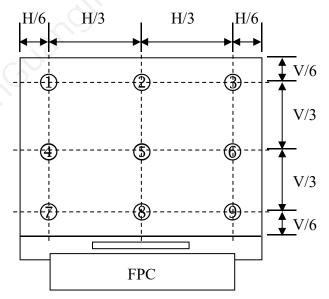
(1) Test Equipment Setup: After stabilizing and leaving the panel alone at a given temperature for 30min, the measurement should be executed. Measurement should be executed in a stable, windless, and dark room 30min after lighting the back-light. This should be measured in the center of screen.



(2) Definition of Contrast Ratio (CR):

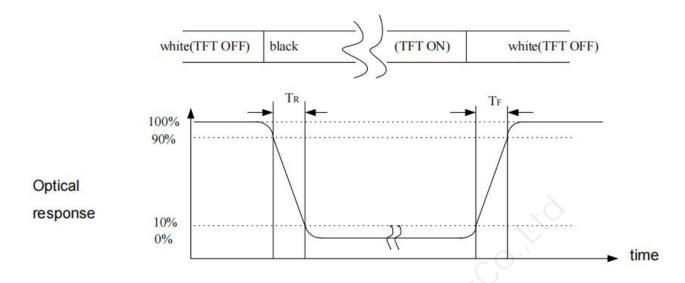
(3) Definition of Luminance Uniformity: Active area is divided into 9 measuring areas (Shown in below), every measuring point is placed at the center of each measuring area.

 $Luminance Uniformity = \frac{\text{Min Luminance of white among 9-points}}{\text{Max Luminance of white among 9-points}} x100\%$ 

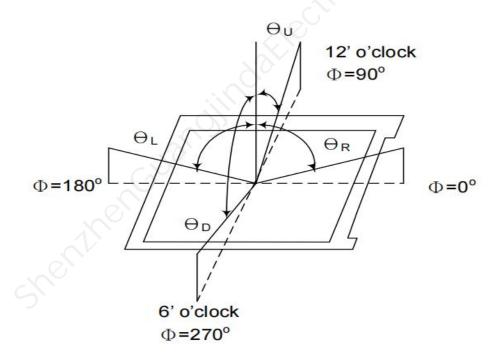


The spot locations for luminance measurement

(4) Definition of Response time: Sum of Tr and Tf.



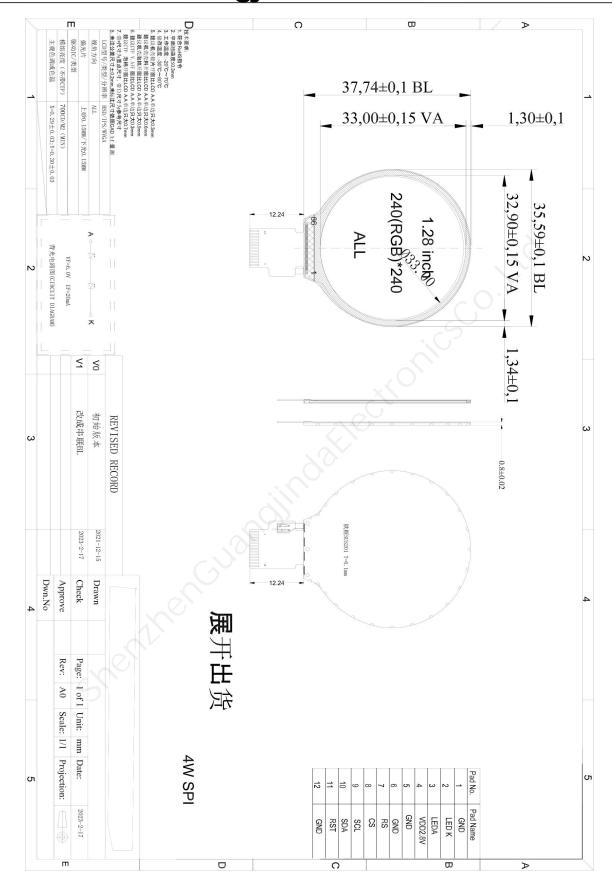
(5) Definition of Viewing Angle: The viewing angle range that the CR≥10.



- (6) Definition of Color Chromaticity (CIE 1931)
  Color coordinate of white & red, green, blue at center point.
- (7) The different Rubbing Direction will cause the different optima view direction.

### **5.MODULE OUTLINE DIMENSION**

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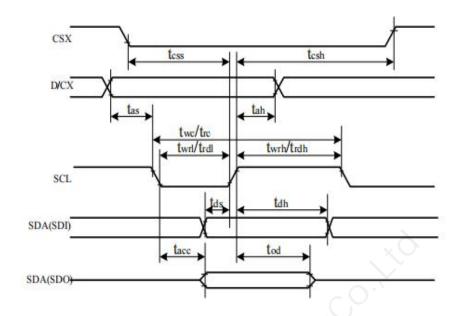
**6.MODULE INTERFACE DESCRIPTION** 

Pin No.	Symbol	Description
1	GND	Power Ground
2	LEDK	Back-light Cathode
3	LEDA	Back-light Anode
4	VCC	Power supply for interface logic circuits(2.8V)
5	GND	Power Ground
6	GND	Power Ground
7	RS	This pin is used serial interface clock
8	CS	Chip select input pin
9	SCL	Serves ascommand or parameter select.
10	SDA	The data is applied on the rising edge of the SCL signal.
11	RST	Reset input pin
12	GND	Power Ground

### **7.REFERENCE APPLICATION CIRCUIT**

Please consult our technical department for detail information.

### 8.TIMINGS FOR SPI Interface



#### Table48.

Signal	Symbol	Parameter	min	max	Unit	Description
CSX  SCL  D/CX  SDA/SDI (Input)  SDA/SD0	tess	Chip select time (Write)	20	10	ns	
CSX	tcsh	Chip select hold time (Read)	40	-	ns	
SCL  D/CX  SDA/SDI (Input)  SDA/SD0	twc	Serial Clock Cycle (Write)	10	-	ns	
	twrh	SCL "H" Pulse Width (Write)	5	-	ns	
	twrl	SCL "L" Pulse Width (Write)	5	-	ns	
	trc	Serial Clock Cycle (Read)	150	-	ns	
	trdh	SCL "H" Pulse Width (Read)	60	-	ns	
	trdl	SCL "L" Pulse Width (Read)	60		ns	
D/CX SDA/SDI	tas	D/CX setup time	10	-	ns	
	tah	D/CX hold time (Write/Read)	10	2	ns	
	tds	Data setup time (Write)	5	-	ns	
	tdh	Data hold time (Write)	5	-	ns	
SDA/SD0 (Output)	tacc	Access time (Read)	10	_	ns	

### 9. RELIABILITY TEST CONDITIONS

No.	Test Item	Test Condition	Notes
1	High Temperature Storage	+80°C / 240H	Inspection after
2	Low Temperature Storage	-30°C / 240H	2~4h storage at room temperature,
3	High Temperature Operating	+70°C / 240H	the sample shall be
4	Low Temperature Operating	-20°C / 240H	free from defects:
5	Temperature Cycle	Ta=-10°C~+25~+50°C,10 Cycle,per30min	1. Air bubble in the LCD; 2. Seal leak;
6	High Temperature /Humidity storage	60°C ,90%RH / 120H	3. Non-display; 4. Missing
7	Vibration Test	Frequency: 10Hz~55Hz~10Hz Amplitude:1.5mm, 2 hours for each direction of X, Y, Z	segments; 5.Glass crack; 6. The surface shall
8	Packing Drop Test	Drop to the ground from 1m height, 1 corner, 3 edges, 6 surfaces.	be free from damage.
9	ESD test	Voltage:±8KV R: 330Ω C: 150pF Air discharge, Three or five times.	7. The electrical characteristics requirements shall be satisfied.

### Remarks:

- (1) The test samples should be applied to only one test item.
- (2) Sample size for each test item is 5~10pcs.
- (3) For High Temperature/Humidity storage test, pure water (resistance>10M $\Omega$ ) should be used.
- (4) In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- (5) Failure judgment criterion: basic specification, electrical characteristic, mechanical characteristic, optical characteristic.

### **10.PACKING SPECIFICATION**

**TBD** 

### 11.INSPECTION CRITERION

Judgement standard							
	Inspe	ction item			Acceptable number		
				Category	A zone	B zone	
	Black spot, White s Bright Spot, Pinhole Foreign Particle,	Pinhole B 0.		Φ≤0.10 0.10<Φ≤0.20 Φ>0.2	Ignored 2 0	Ignored	
	Bubble and Particle Between polarizer a glass, scratch on po	and $\Phi = (a+b)/2(mm)$		Total defective point(B,C)	3		
		Bright spot		0.15<Φ≦0.20	N≤2	Ignored	
		Dark spot/ Black spot		0.15<Φ≦0.20	N≤2		
1	Dival maint	Attached to the two pixels bright spots	are	0.15<Φ≦0.20	N≤2		
	Pixel point defect	Even a two pixel is dark		0.15<Φ≦0.20	N≤2		
		Pixel total number		0.15<Φ≦0.20	N≤2		
		to the defect of the foreign	gn bo	by foreign matter is judged and by dy.  wired to show the type of defe	_		
2	Black line, White line, Bubble and Particle Between Polarizer and	bble and Between		W≤0.03 L≤3.0 0.03 <w≤0.05 l≤3.0<br="">0.05<w< td=""><td>Ignored 2 0</td><td>Ignored</td></w<></w≤0.05>	Ignored 2 0	Ignored	
	glass, Scratch on polarizer	L W:Width, L:Length(mm)		Total defective point(B,C)	2		
	Contrast	<b>1</b>	Α	Ф≦0.1	Ignored	Ignored	
3	variation	b	B C	0.1<Φ≦0.3 Φ>0.3	0		
	5	$\begin{vmatrix} a \\ & \Rightarrow \end{vmatrix}$ $\Phi = (a+b)/2 (mm)$		Total defective point(B,C)	2		
4	Bubble inside cell			any size	none	none	
	Polarizer defect	Scratch and damage on polarizer, particle on polarizer or between polarizer and glass.		er to item 1 and item 2.			
5	(if Polarizer is used)	Bubble, dent and convex	A B C	Φ≦0.3 0.3<Φ≦0.5 0.5<Φ	Ignored 2 0	Ignored	
				Total defective point(B,C)	2		

				Judgement standard			
	Inspection item	Category		Acceptable number			
			,	A zone	B zone		
	Surplus glass	①Stage surplus glass		b ≦ 0.3mm			
6		glass			outline dimension and assembling.		
	MURA	①MURA	not is r No inst not Ins (M	Naked eye examination: red, green, blue screen does not allow the appearance, black screen requires visual is not obvious, the specific reference limit samples.  Note: the principle of closing the sample is to be installed on the whole machine and the end user will not find it in the normal usage scenario.  Inspection basis: 6%ND  (MURA mainly in the black screen and indoor light is relatively dark will be found, it is recommended to turn off the indoor lighting inspection.)			
7		②Point Black / WIpoint(MURA)	D≦ 0. I D>0 2, s screen		d; ,N≦2;		

			Judgment standard			
	Inspection item			Category(application: B zone)		
		①The front of lead terminals	Α	If a≦t and b ≦1.0, c is not limited		
	Glass defect crack	b		a≦t, 1≦b≦2mm, c≦3mm		
				If glass crack cover alignment mark, b≦0.5mm.		
		w t	D	Crack at two sids of lead terminals should not cover patterns and alignment mark		
		②Surrounding				
		crack—non-contact side				
		seal				
		c b a		h a lawar hardarlina of the cool		
				b < Inner borderline of the seal		
		Inner border line of the seal				
		Outer border line of the seal		•		
8		③ Surrounding crack— contact		b < Outer borderline of the seal		
		side				
		seal t a				
		Inner border line of the seal Outer border line of the seal				
		(4) Corner	Α	$a \le t, b \le 3.0, c \le 3.0$		
			*Glas	ss crack should not cover patterns used for		
		w c				

		Inspection item	Judgement standard
	FPC defect	Component soldering: No cold soldering, short/open circuit, burr, tin ball.  The flat encapsulation component position deviation must be less than 1/2 width of the pin (Pic.1);  The sheet component deviation: pin deviates from the pad and contact with the near components is not permitted (Pic.2)	Component  L≤W/2  W
9		lead defect: The lead lack must be less than 1/2of its width; The lead burr must be less than 1/2 of the seam; Impurities connect with the near leads is not permitted	Soldering pad Lead  Component  L1>0
		Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	Soldering tin is not permit in this area  Soldering tin is not permit in this area  Socket  Base Board

#### 12.GENERAL PRECAUTIONS

#### 1.1 HANDING

- (1) When the module is assembled, it should be attached to the system firmly. Be careful not to twist and bent the module.
- (2) Refrain from strong mechanical shock and / or any force to the module. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that display modules are very fragile and could be easily damaged. Do not press or scratch the surface harder than a HB pencil lead.
- (4) Wipe off water droplets or oil immediately. If you leave the droplets for a long time, straining and discoloration may occur.
- (5) If the display module surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, should be wiped by moisten cloth with isopropyl alcohol or ethyl alcohol solvents, DO NOT with water, ketone type materials (e.g. acetone), aromatic, toluene, ethyl acid or methyl chloride, and so on.
- (6) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs or clothes, it must be washed away thoroughly with soap.
- (7) Use finger-stalls with sort gloves in order to keep display clean during the incoming inspection and assembly process.
- (8) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (9) Do not touch directly conductive parts such as the CMOS LSI pad and the interface terminals with bare hands, therefore operations should be grounded whenever he/she comes into contact with the modules.
- (10) Do not exceed the absolute maximum rating value. (The supply voltage variation, input voltage variation, variation in part contents and environmental temperature, and so on), otherwise the module may be damaged.

#### 1.2 SOLDERING

- (1) Use soldering irons with proper grounding and no leakage.
- (2) For No RoHS Product: soldering temperature is 290~350°C, soldering time is 3~5s; for RoHS Product: soldering temperature is 340~370°C, soldering time is 3~5s.
- (3) If soldering flux is used, be sure to remove any remaining flux after soldering (This does not apply in the case of a non-halogen type of flux).

#### 1.3 STORAGE

- (1) DO NOT leave the module in high temperature and high humidity for a long times, keep the temperature from 0°C to 35°C and relative humidity of less than 60%.
- (2) It is highly recommended to store the module in a dark place. The Liquid crystal is deteriorated by ultraviolet, DO NOT leave it in direct sunlight and strong ultraviolet ray for many hours.